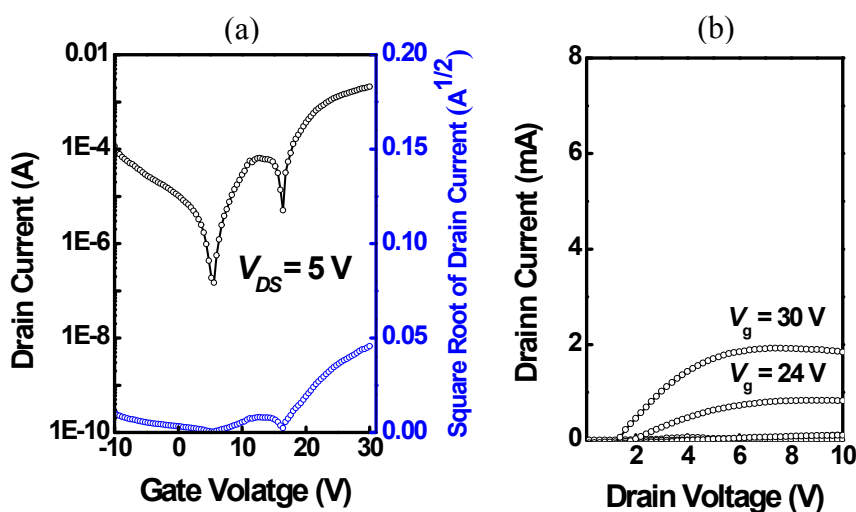


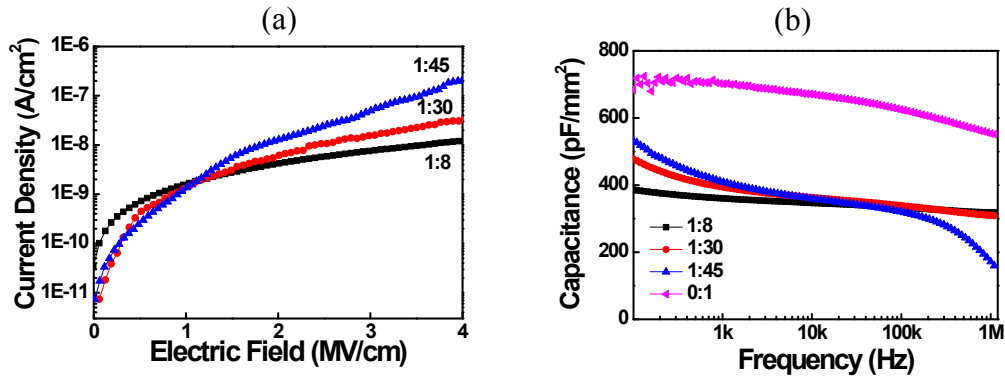
## Soluble oxide gate dielectrics prepared using the self-combustion reaction for high-performance thin-film transistors

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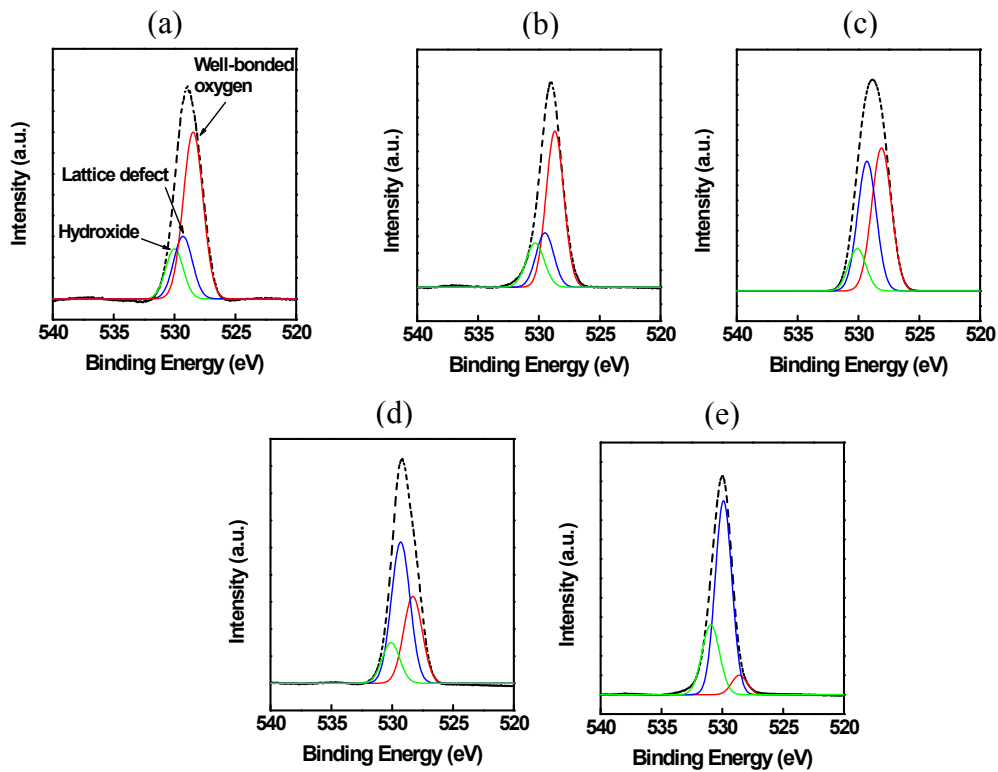
*Additional Figures*



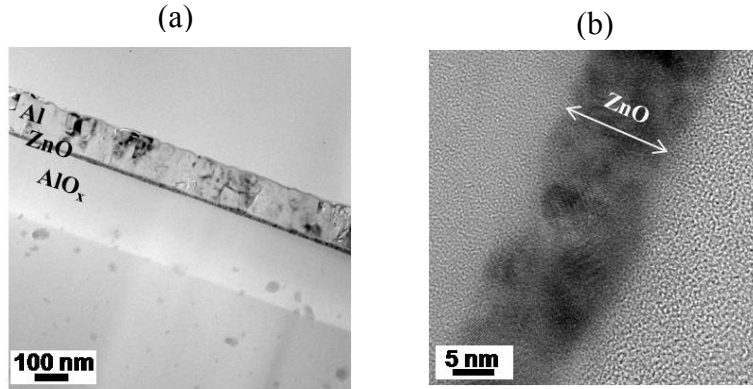
**Fig. S1** (a) The transfer and (b) output characteristics of ZnO TFT fabricated from non-combustive  $\text{AlO}_x$  gate dielectric with  $\text{Al}(\text{C}_2\text{H}_5\text{O}_2)_3$  precursor with GPTMS.



**Fig. S2** (a) Current density vs. electrical field and (b) dependence of capacitance on the frequency for self-combustive  $\text{AlO}_x$  thin films with various amounts of GPTMS.

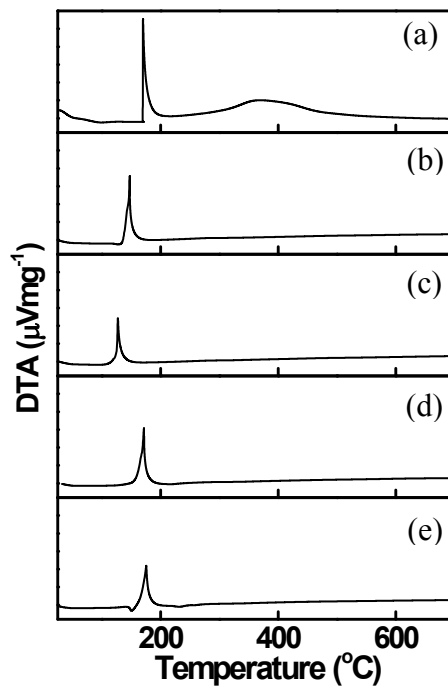


**Fig. S3** XPS spectra of  $\text{AlO}_x$  thin films prepared from various precursors: (a) self-combustive  $\text{AlO}_x$  precursor, (b) self-combustive  $\text{AlO}_x$  precursor with GPTMS, (c) combustive precursor with urea, (d) noncombustive  $\text{Al}(\text{NO}_3)_3 \cdot 9\text{H}_2\text{O}$ , and (e) noncombustive  $\text{Al}(\text{C}_2\text{H}_5\text{O}_2)_3$ .

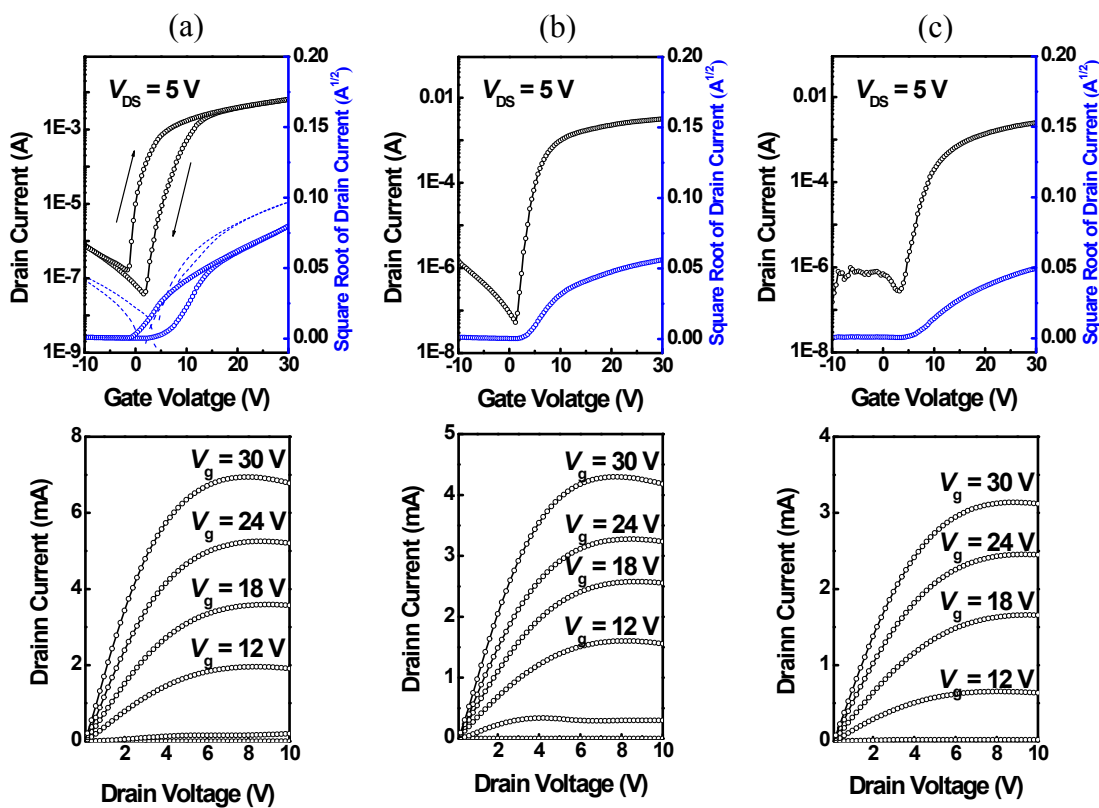


**Fig. S4** TEM cross sectional images of the ZnO TFT with self-combustive  $\text{AlO}_x$  gate dielectric:

(a) cross sectional TEM image of ZnO TFT and (b) cross sectional TEM image of magnified ZnO layer between  $\text{AlO}_x$  gate dielectric and Al electrode.



**Fig. S5** TG-DTA curves of combustive  $\text{AlO}_x$  precursors with different ratios of  $\text{Al}(\text{C}_2\text{H}_5\text{O}_2)_3$  to  $\text{Al}(\text{NO}_3)_3 \cdot 9\text{H}_2\text{O}$ : (a)  $\text{Al}(\text{C}_2\text{H}_5\text{O}_2)_3/\text{Al}(\text{NO}_3)_3 \cdot 9\text{H}_2\text{O} = 1/1$ , (b)  $\text{Al}(\text{C}_2\text{H}_5\text{O}_2)_3/\text{Al}(\text{NO}_3)_3 \cdot 9\text{H}_2\text{O} = 1/2$ , (c)  $\text{Al}(\text{C}_2\text{H}_5\text{O}_2)_3/\text{Al}(\text{NO}_3)_3 \cdot 9\text{H}_2\text{O} = 1/3$ , (d)  $\text{Al}(\text{C}_2\text{H}_5\text{O}_2)_3/\text{Al}(\text{NO}_3)_3 \cdot 9\text{H}_2\text{O} = 2/1$ , and (e)  $\text{Al}(\text{C}_2\text{H}_5\text{O}_2)_3/\text{Al}(\text{NO}_3)_3 \cdot 9\text{H}_2\text{O} = 3/1$ .

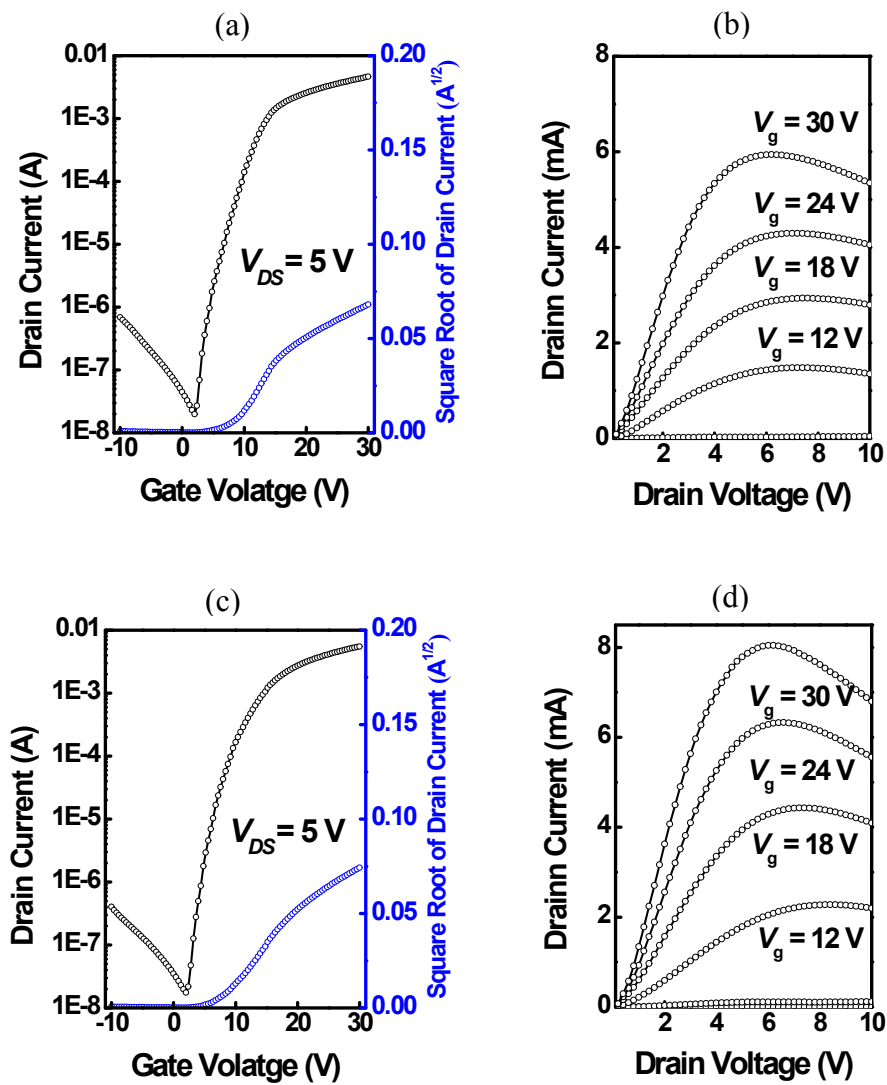


**Fig. S6** Transfer and output characteristics of the ZnO TFTs fabricated from  $\text{AlO}_x$  gate dielectrics with 1:8 ratios of the self-combustive  $\text{AlO}_x$  precursor to GPTMS depending on different composition ratios of  $\text{Al}(\text{C}_2\text{H}_5\text{O}_2)_3$  to  $\text{Al}(\text{NO}_3)_3 \cdot 9\text{H}_2\text{O}$ : (a)  $\text{Al}(\text{C}_2\text{H}_5\text{O}_2)_3/\text{Al}(\text{NO}_3)_3 \cdot 9\text{H}_2\text{O} = 1/1$ , (b)  $\text{Al}(\text{C}_2\text{H}_5\text{O}_2)_3/\text{Al}(\text{NO}_3)_3 \cdot 9\text{H}_2\text{O} = 1/3$ , (c)  $\text{Al}(\text{C}_2\text{H}_5\text{O}_2)_3/\text{Al}(\text{NO}_3)_3 \cdot 9\text{H}_2\text{O} = 3/1$ .

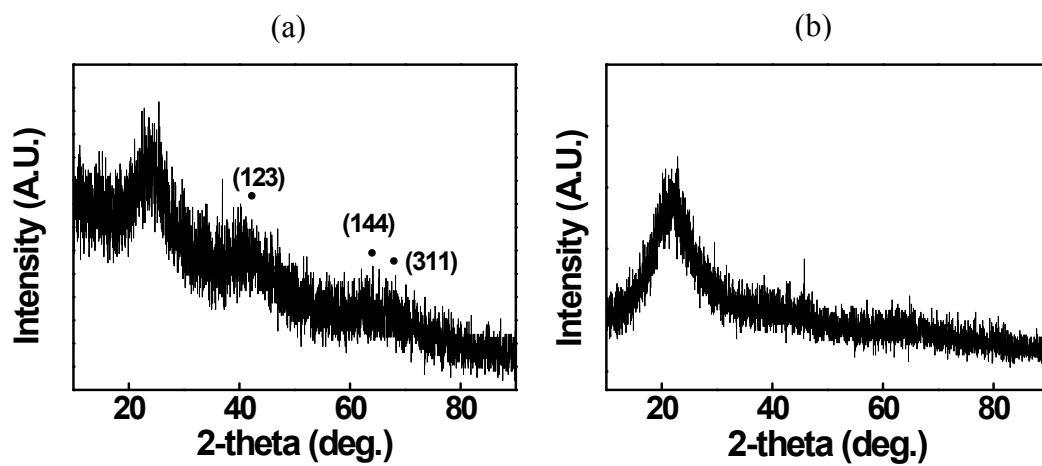
**Table S1** Characteristics of ZnO TFTs fabricated from AlO<sub>x</sub> gate dielectrics with 1:8 ratios of the self-combustive AlO<sub>x</sub> precursor to GPTMS depending on different composition ratios of Al(C<sub>2</sub>H<sub>5</sub>O<sub>2</sub>)<sub>3</sub>: Al(NO<sub>3</sub>)<sub>3</sub>·9H<sub>2</sub>O

molar ratio (Al(C <sub>2</sub> H <sub>5</sub> O <sub>2</sub> ) <sub>3</sub> : Al(NO <sub>3</sub> ) <sub>3</sub> ·9H <sub>2</sub> O)	mobility <sup>a</sup> (cm <sup>2</sup> V <sup>-1</sup> s <sup>-1</sup> )	threshold voltage (V)	on/off ratio
1:1	24.7	6.35	1.71E + 05
1:3	20.6	3.04	6.00E + 04
3:1	6.56	5.61	1.610E + 04

<sup>a</sup>Calculated from capacitance values extrapolated to a frequency of 1 Hz



**Fig. S7** (a) Transfer and (b) output characteristics of the ZnO TFTs fabricated from  $AlO_x$  gate dielectrics with 1:30 ratios of the self-combustive  $AlO_x$  precursor to GPTMS. (c) Transfer and (d) output characteristics of the ZnO TFTs fabricated from  $AlO_x$  gate dielectrics with 1:45 ratios of the self-combustive  $AlO_x$  precursor to GPTMS.



**Fig. S8** XRD pattern of the (a) self-combustive and (b) non-combustive  $\text{AlO}_x$  films deposited on the glass substrate after annealing at  $250^\circ\text{C}$ .